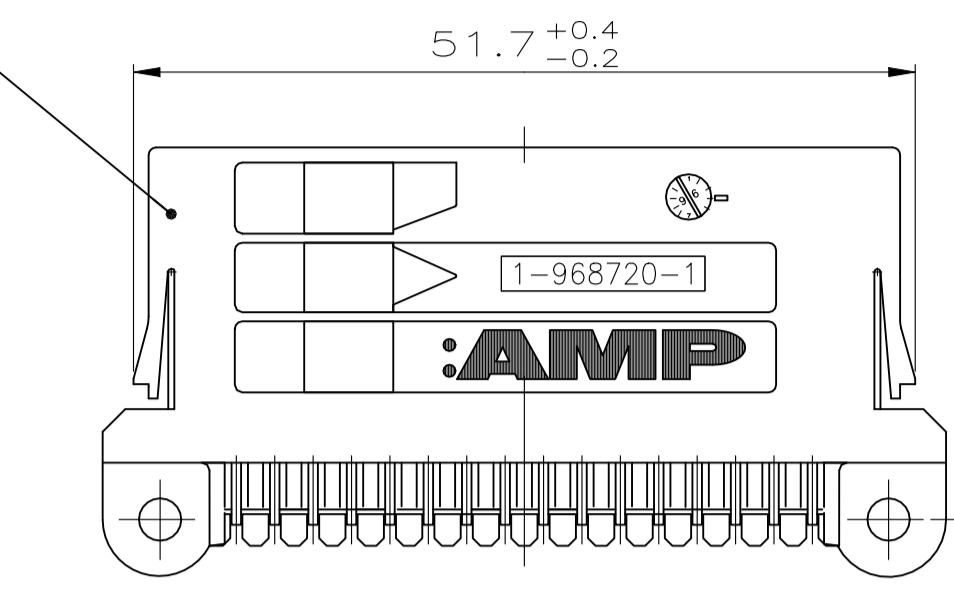


LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DIN	APVD
95-52434	-	B EGAO 2378 04	26.10.04	C.BeU	TS
		B1 EGAO 2744 04	23.12.04	C.BeU	TS
		B2 ECR-05-001464	07.04.05	C.BeU	TS
		B3 ECR-22-127258	20JAN2022	MSA	KHI

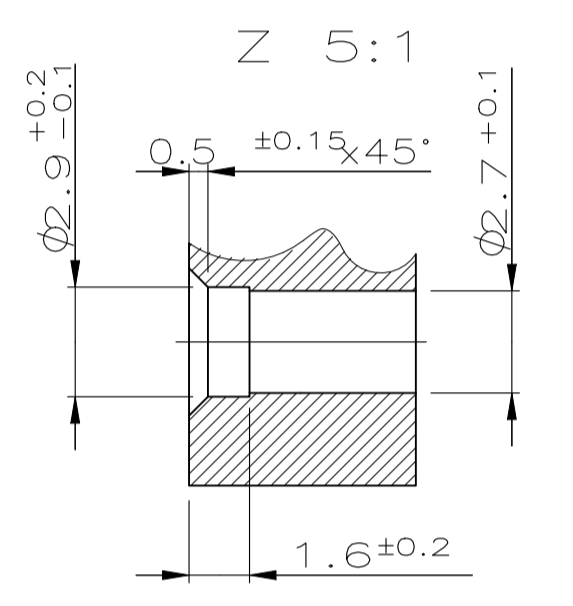
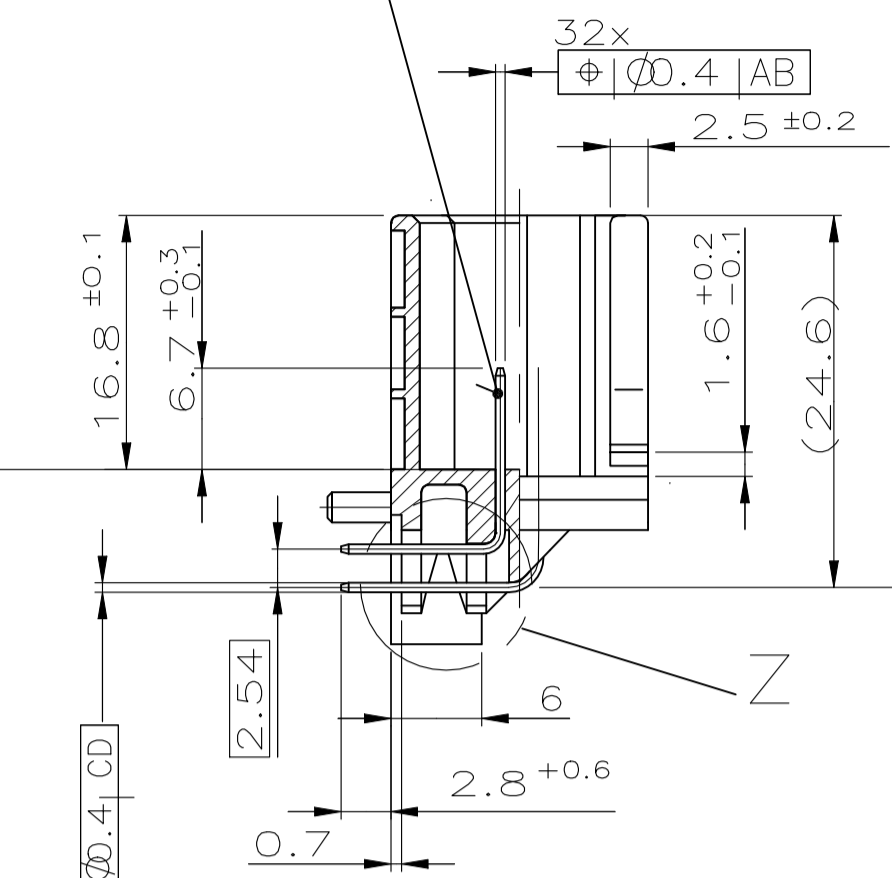
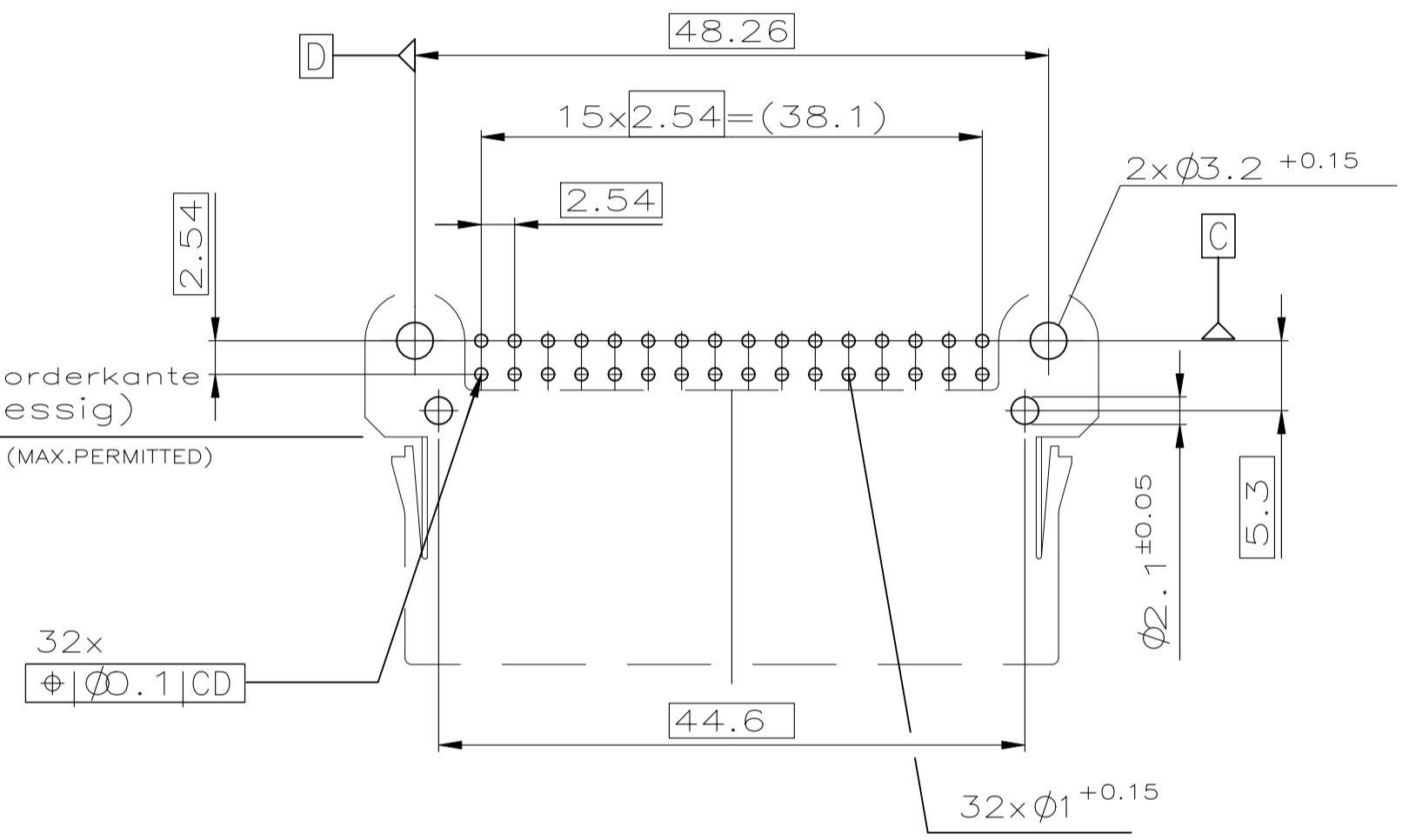
Stiftwanne / PIN HEADER  
 MATERIAL:  
 Werkst.:siehe Tabelle/SEE TABLE  
 Farbe/COLOR: siehe Tabelle/SEE TABLE

2 Kontaktstift/CONTACT PIN  
 siehe Zeichnung AMP 114-18063

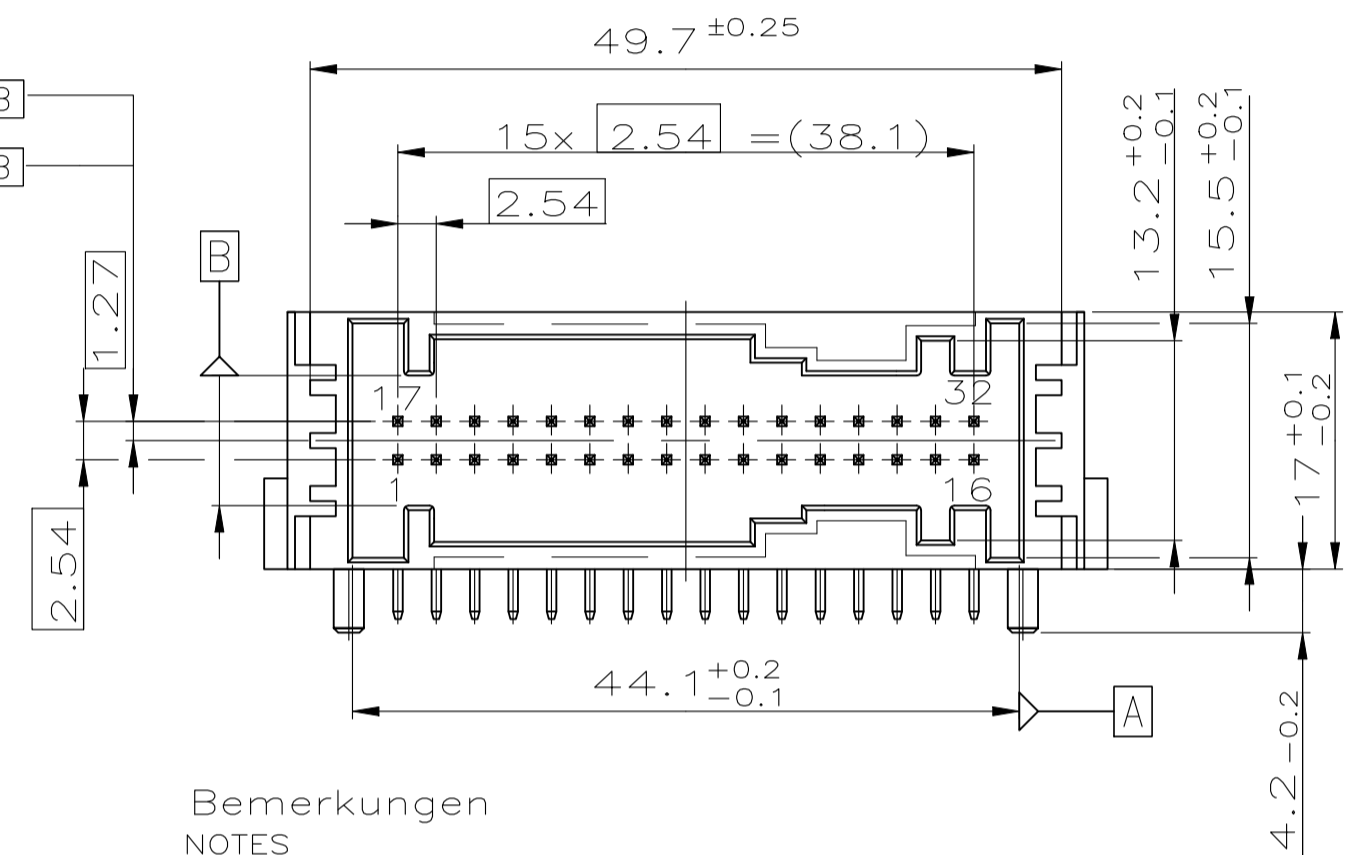
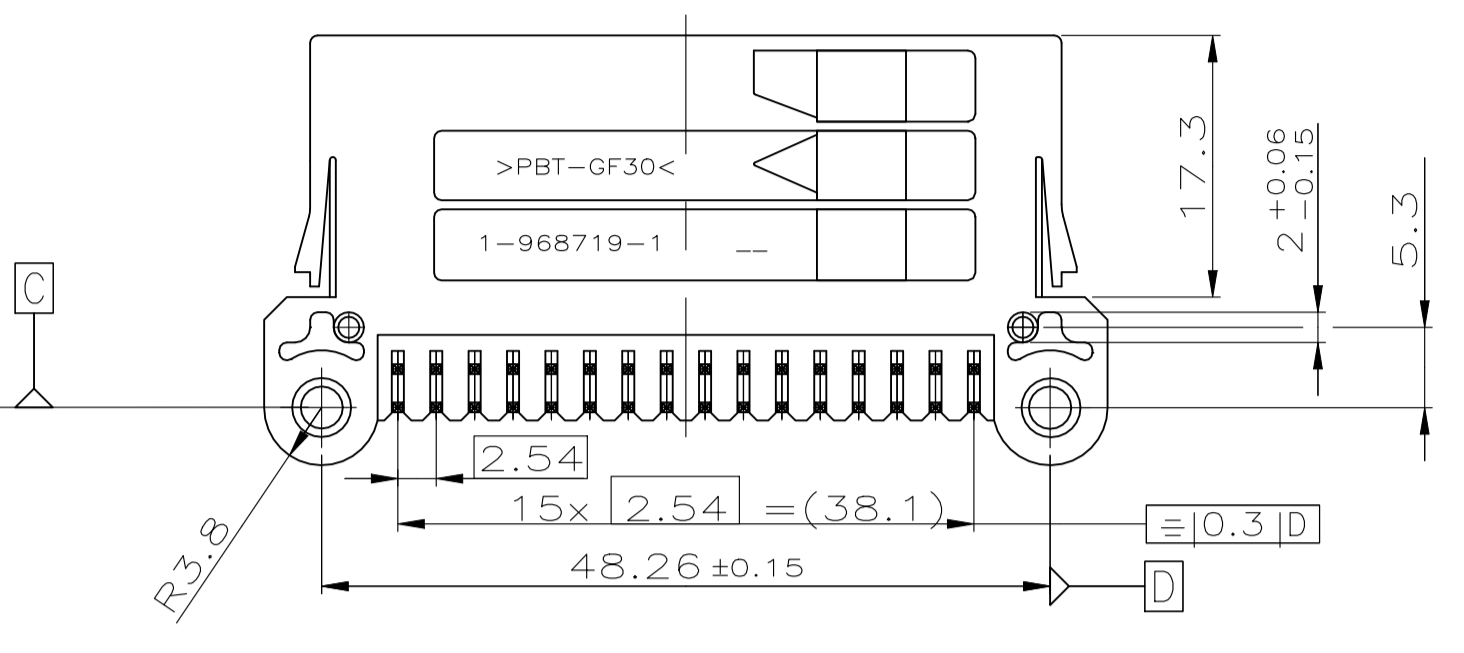
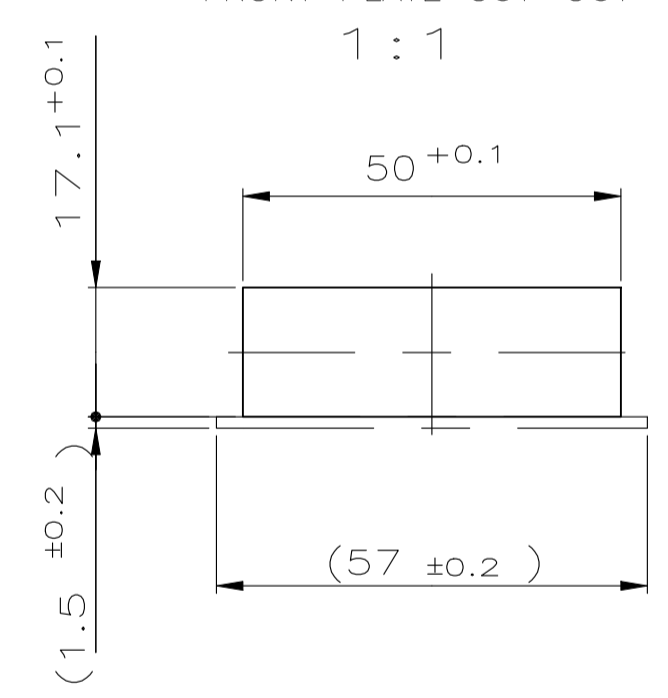


Leiterplattenlayout (Bestückungsseite)  
 PCB-LAYOUT (MOUNTING SIDE)

Leiterplattenvorderkante  
 (max.zulaessig)  
 PCB FRONT EDGE (MAX.PERMITTED)



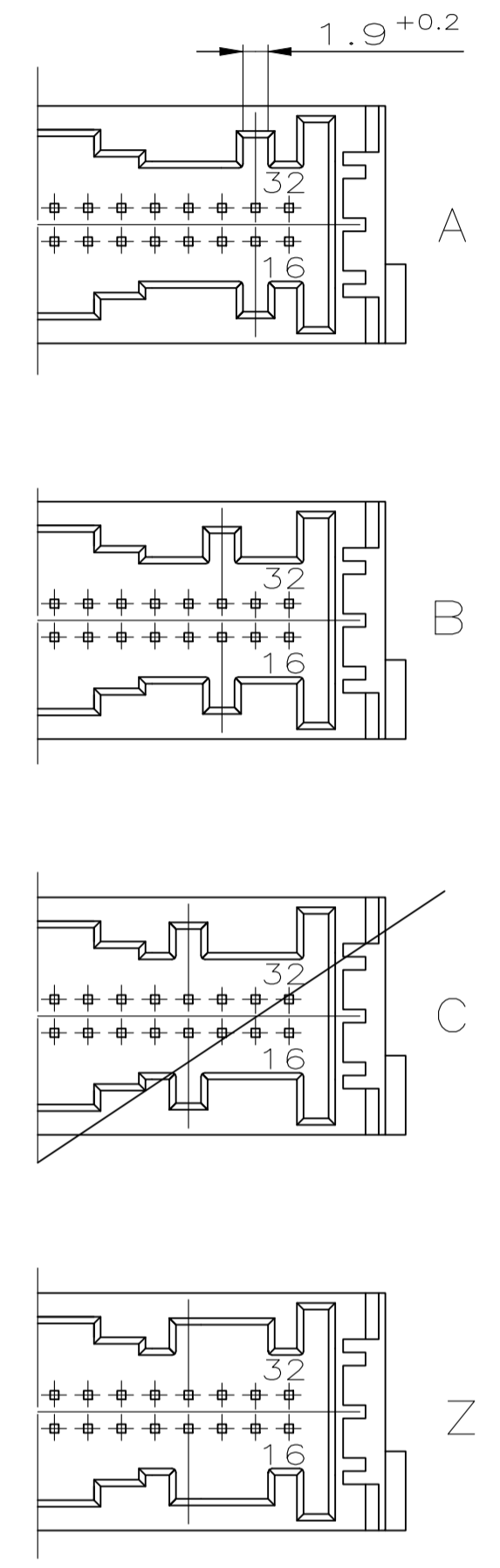
Frontplattenausschnitt  
 FRONT PLATE CUT-OUT



Bemerkungen  
 NOTES

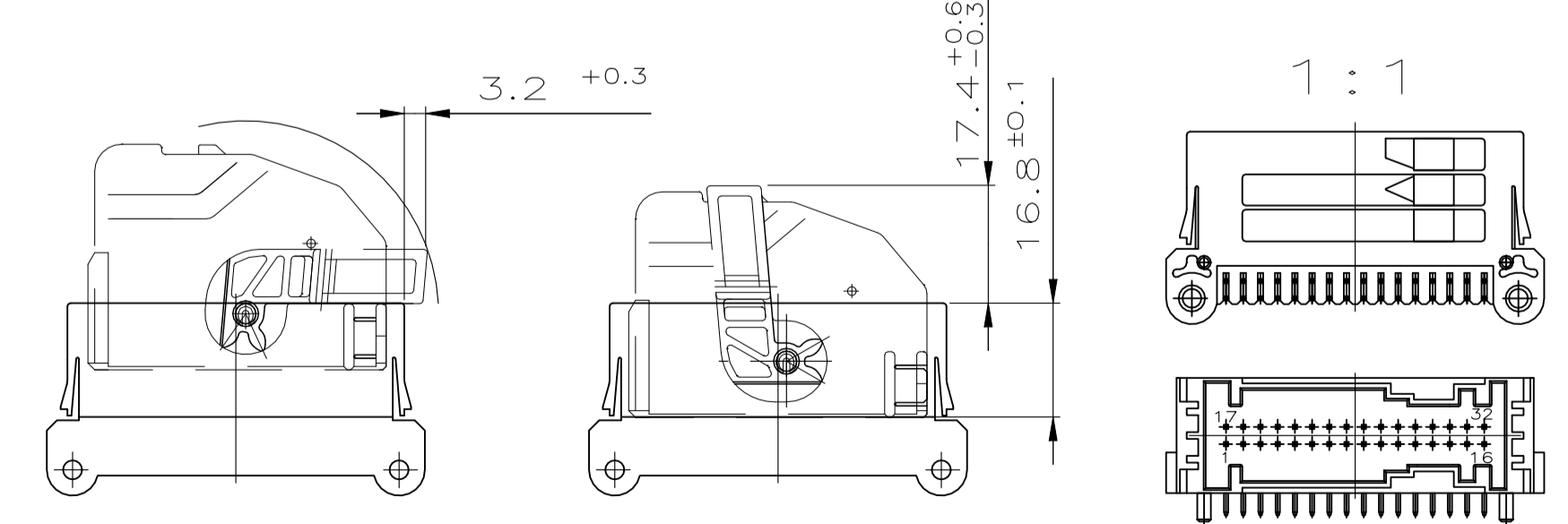
- Maßgebend ist der deutsche Text  
 ONLY THE GERMAN-LANGUAGE VERSION SHALL BE BINDING
- Lötbarkeit gemäß DIN IEC 60068-2-20, Alterung 3  
 SOLDERABILITY ACCORDING TO DIN IEC 60068-2-20, AGEING 3
- Kontaktausdrückkraft >25N mit Vorschub 25mm/min  
 PRESS OUT FORCE >25N WITH FORCE 25mm/min
- Kodierung A gezeichnet  
 CODING A AS SHOWN
- Anwendbar fuer Reflow-Loetprozess  
 APPLICABLE FOR REFLOW SOLDERING PROCESS
- Verpackung:Produkttraeger  
 PACKAGING:TRAY
- Formteilungsgrat max.0.3 zulaessig  
 MOULD BURRS MAX.0.3 PERMITTED
- Einzelheiten der Ausfuehrung bleiben dem Hersteller ueberlassen  
 DETAILS OF DESIGN ARE LEFT TO MANUFACTURER

Kodierungen  
 CODING



Freiraum für Hebel  
 in Vorraststellung  
 an Stiftwanne  
 FREE AREA FOR LEVER  
 IN PRELOCKED POSITION  
 AT PIN HEADER

Freiraum für Hebel  
 in Endraststellung  
 an Stiftwanne  
 FREE AREA FOR LEVER  
 IN ENDOCKED POSITION  
 AT PIN HEADER



2-968720-4	B	B	Hergestellt aus PN 2-968720-2,verpackt in Verpackungsschale MADE FROM PN.2-968720-2,PACKAGING IN TRAY																		
1-968720-4	B	A	Hergestellt aus PN 1-968720-2,verpackt in Verpackungsschale MADE FROM PN.1-968720-2,PACKAGING IN TRAY																		
1-968720-3	B	A	Hergestellt aus PN 1-968720-2,verpackt in Verpackungsrohr MADE FROM PN.1-968720-2,PACKAGING IN TUBE																		
2-968720-2	B	B	2	Stiftkontakt/PIN CONTACT	5	TIN PLATING VERZINNT	S	12.4	2-967348-1	0-965612-1	0-965343-1										
			1	Stiftwanne/PIN HEADER		SPS-GF20	natur/NATURAL														
1-968720-2	B	A	2	Stiftkontakt/PIN CONTACT	5	TIN PLATING VERZINNT	S	12.4	1-967348-1	0-965612-1	0-965343-1										
			1	Stiftwanne/PIN HEADER		SPS-GF20	schwarz/BLACK														
9-968720-1	B	Z	2	Stiftkontakt/PIN CONTACT		GOLD PLATING vergoldet	S	12.4	9-968775-1	968778-1	-										
			1	Stiftwanne/PIN HEADER		PBT-GF30	wasserblau WATER BLUE														
1-968720-1	B	A	2	Stiftkontakt/PIN CONTACT		GOLD PLATING vergoldet	S	12.4	1-968775-1												
			1	Stiftwanne/PIN HEADER		PBT-GF30	schwarz/BLACK														
AMP BESTELL-NR. ORDER NO.	REV.	KOD. COD.	REV.	BENENNUNG DESCRIPTION	Werkstoff MATERIAL	OBERFLÄCHE FARBE SURFACE/COLOUR	ART KIND	GRAMM GEWICHT	PASSEND ZU: Abdeckkappe SUITABLE FOR: SHIELD	DAZU GEHÖRT: Buchsengehäuse USED WITH: SOCKET HOUSING	DAZU GEHÖRT: Decke USED WITH: LEVEL										

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED: ALLE DIMENSIONEN UNLESS OTHERWISE SPECIFIED: ALLE DIMENSIONEN TOLERANZEN		DIN		TE Connectivity	
mm		0 PL	± 0.140	C.BeU	10-AUG-00	MOS, PIN HEADER, 32 POS. MOS, Stiftwanne, 32-polig	
		1 PL	± 0.100	CIK	10-AUG-00	NAME	
		2 PL	± 0.075	T.Stieler		PRODUCT SPEC	
		3 PL	± 0.050	APVD		108-18214	
		4 PL	± 0.025	NAME		APPLICATION SPEC	
		ANGLES/WINKEL	± 0.5	SIZE		DRAWING NO	
MATERIAL	FINISH			WEIGHT		00779	
				12.4g		C=968720	
				CUSTOMER DRAWING		SCALE 2:1 SHEET 1 of 1 REV B3	